Octal D-Type Flip-Flop with 3-State Outputs

The MC74ACT564 is a high–speed, low power octal flip–flop with a buffered common Clock (CP) and a buffered common Output Enable (\overline{OE}) .

The information presented to the D inputs is stored in the flip-flops on the LOW-to-HIGH Clock (CP) transition.

The MC74ACT564 device is functionally indentical to the MC74ACT574, but with inverted outputs.

Features

- Inputs and Outputs on the Opposite Sides of the Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessor
- Functionally Indentical to the MC74ACT574 but with Inverted Outputs
- 3-State Outputs for Bus-Oriented Applications
- Outputs Source/Sink 24 mA
- TTL Compatible Inputs
- Pb-Free Packages are Available*

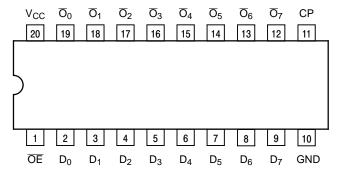


Figure 1. Pinout: 20-Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D ₀ –D ₇	Data Inputs
СР	Clock Pulse Input
ŌĒ	3-State Output Enable Input
$\overline{O}_0 - \overline{O}_7$	3-State Outputs

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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PDIP-20 N SUFFIX CASE 738



SOIC-20W DW SUFFIX CASE 751D

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 5 of this data sheet.

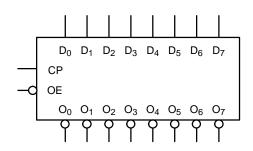
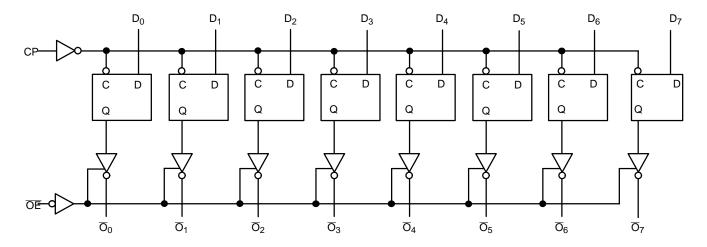


Figure 2. Logic Symbol



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

FUNCTION TABLE

	Inputs		Internal	Outputs	Function
ŌĒ	СР	D	Q	0	runction
Н	Н	L	NC	Z	Hold
Н	Н	Н	NC	Z	Hold
Н	工	L	Н	Z	Load
Н	工	Н	L	Z	Load
L	工	L	Н	Н	Data Available
L	上	Н	L	L	Data Available
L	Н	L	NC	NC	No Change in Data
L	Н	Н	NC	NC	No Change in Data

H = HIGH Voltage Level

L = LOW Voltage Level X = Immaterial

Z = High Impedance

_ = LOW-to-HIGH Transition

NC = No Change

FUNCTIONAL DESCRIPTION

The MC74ACT564 consists of eight edge-triggered flip-flops with individual D-type inputs and 3-state complementary outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that

meet the setup and hold times requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable (\overline{OE}) LOW, the contents of the eight flip-flops are available at the outputs. When \overline{OE} is HIGH, the outputs go to the high impedance state. Operation of the \overline{OE} input does not affect the state of the flip-flops.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \le V_{I} \le V_{CC} + 0.5$	V
Vo	DC Output Voltage (Note 1)		$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±50	mA
Io	DC Output Sink/Source Current		±50	mA
I _{CC}	DC Supply Current per Output Pin		±50	mA
I _{GND}	DC Ground Current per Output Pin		±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature under Bias		+150	°C
θ_{JA}	Thermal Resistance	PDIP SOIC	67 96	°C/W
P_{D}	Power Dissipation in Still Air at 85°C	PDIP SOIC	750 500	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen Index: 30% – 35%		UL 94-V0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)		> 2000 > 200 > 1000	V
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 85°C (Note 5)		±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I_O absolute maximum rating must be observed.

- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	DC Input Voltage (Referenced to GND)	4.5		5.5	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0		V _{CC}	V
T _A	Operating Temperature, All Package Types	-40	25	+85	°C
t _r , t _f	Input Rise and Fall Time (Note 7) $V_{CC} = 4$ $V_{CC} = 5$	1.5 V 0 5.5 V 0	10 8.0	10 8.0	ns/V
TJ	T _J Junction Temperature (PDIP)			140	°C
I _{OH}	Output Current – High			-24	mA
I _{OL}	Output Current – Low			24	mA

^{6.} Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.

^{7.} V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

		v _{cc}	T _A = -	+25°C	T _A = -40°C to +85°C		
Symbol	Parameter	(V)			Guaranteed Limits		Conditions
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V V	I _{OUT} = -50 μA
		4.5 5.5		3.86 4.86	3.76 4.76	V V	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH} $ -24 mA -24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V V	I _{OUT} = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	V V	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH}$ 24 mA $^{2}V_{IOL}$ 24 mA
I _{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μΑ	V _I = V _{CC} , GND
ΔI_{CCT}	Additional Max. I _{CC} /Input	5.5	0.6		1.5	mA	V _I = V _{CC} – 2.1 V
I _{OZ}	Maximum 3–State Current	5.5		±0.5	±5.0	μΑ	$ \begin{array}{l} V_{I}\left(OE\right) = V_{IL}, \ V_{IH} \\ V_{I} = V_{CC}, \ GND \\ V_{O} = V_{CC}, \ GND \end{array} $
I _{OLD} I _{OHD}	†Minimum Dynamic Output Current	5.5 5.5			75 –75	mA mA	V _{OLD} = 1.65 V Max V _{OHD} = 3.85 V Min
Icc	Maximum Quiescent Supply Current	5.5		8.0	80	μΑ	V _{IN} = V _{CC} or GND

^{*}All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS $t_r = t_f = 3.0$ ns (For Figures and Waveforms, See Figures 4, 5, and 6.)

Symbol	mbol Parameter		V _{CC} *		T _A = +25°C C _L = 50 pF		$T_A = -40$ °C to +85°C $C_L = 50 \text{ pF}$		Unit
			(V)	Min	Тур	Max	Min	Max	
f _{max}	Maximum Clock Frequency		5.0	85	-	_	75	-	MHz
t _{PLH}	Propagation Delay	CP to \overline{Q}_n	5.0	2.0	_	10.5	1.5	11.5	ns
t _{PHL}	Propagation Delay	CP to \overline{Q}_n	5.0	1.5	_	9.5	1.5	10.5	ns
t _{PZH}	Output Enable Time		5.0	1.5	_	9.0	1.5	9.5	ns
t _{PZL}	Output Enable Time		5.0	1.5	_	8.5	1.0	9.5	ns
t _{PHZ}	Output Disable Time		5.0	1.5	_	10.5	1.5	11.5	ns
t _{PLZ}	Output Disable Time		5.0	1.5	-	8.0	1.0	8.5	ns

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V

AC OPERATING REQUIREMENTS

Symbol	ymbol Parameter		V _{CC} * (V)		Γ _A = +25°C C _L = 50 pF	$T_A = -40$ °C to +85°C $C_L = 50$ pF	Unit
			(٧)	Тур	Guaran	teed Minimum	
t _s	Setup Time, HIGH or LOW	D _n to C _P	5.0	_	2.5	3.0	ns
t _h	Hold Time, HIGH or LOW	D _n to C _P	5.0	_	1.0	1.0	ns
t _w	C _P Pulse Width	HIGH or LOW	5.0	_	3.0	3.5	ns

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V.

CAPACITANCE

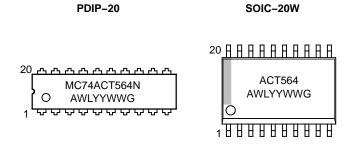
Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}			pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device	Package	Shipping [†]	
MC74ACT564N	PDIP-20		
MC74ACT564NG	PDIP-20 (Pb-Free)	18 Units / Rail	
MC74ACT564DWR2	SOIC-20		
MC74ACT564DWR2G	SOIC-20 (Pb-Free)	1000 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MARKING DIAGRAMS

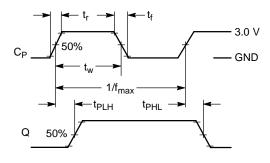


A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

^{*}Voltage Range 5.0 V is 5.0 V ± 0.5 V.

SWITCHING WAVEFORMS



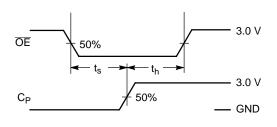


Figure 4.

Figure 5.

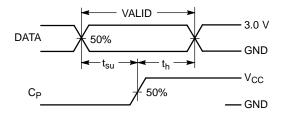
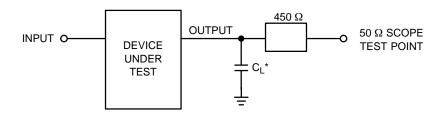


Figure 6.

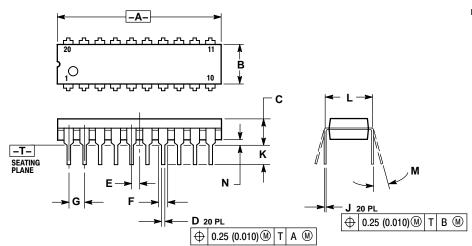


*Includes all probe and jig capacitance

Figure 7. Test Circuit

PACKAGE DIMENSIONS

PDIP-20 **N SUFFIX** PLASTIC DIP PACKAGE CASE 738-03 ISSUE E

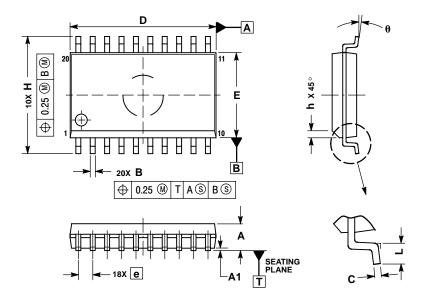


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INC	HES	MILLIM	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	1.010	1.070	25.66	27.17	
В	0.240	0.260	6.10	6.60	
С	0.150	0.180	3.81	4.57	
D	0.015	0.022	0.39	0.55	
E	0.050	BSC	1.27 BSC		
F	0.050	0.070	1.27	1.77	
G	0.100	BSC	2.54	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.140	2.80	3.55	
L	0.300	BSC	7.62	BSC	
M	0°	15°	0°	15°	
N	0.020	0.040	0.51	1.01	

PACKAGE DIMENSIONS

SOIC-20W **DW SUFFIX** CASE 751D-05 **ISSUE G**



- 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES
 PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS					
DIM	MIN	MAX				
Α	2.35	2.65				
A1	0.10	0.25				
В	0.35	0.49				
C	0.23	0.32				
D	12.65	12.95				
Е	7.40	7.60				
e	1.27	BSC				
H	10.05	10.55				
h	0.25	0.75				
۲	0.50	0.90				
θ	0°	7 °				

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